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SUBMISSION TYPE:	NEW ASSIGNMENT
NATURE OF CONVEYANCE:	ASSIGNMENT

CONVEYING PARTY DATA

Name	Execution Date
Makoto Aikawa	09/27/2007
lwao Takiguchi	10/01/2007
Tetsuji Tamura	09/27/2007

RECEIVING PARTY DATA

Name:	Sony Computer Entertainment Inc.	
Street Address:	2-6-21 Minami-Aoyama, Minato-Ku	
City:	Minato-ku, Tokyo	
State/Country:	JAPAN	
Postal Code:	107-0062	

PROPERTY NUMBERS Total: 1

Property Type	Number
Application Number:	11927840

CORRESPONDENCE DATA

Fax Number: (512)823-1036

Correspondence will be sent via US Mail when the fax attempt is unsuccessful.

Phone: 5128231003

Email: abdeniso@us.ibm.com

Correspondent Name: D'Ann N. Rifai
Address Line 1: 11400 Burnet Road

Address Line 2: IBM-Intellectual Property Law Address Line 4: Austin, TEXAS 78758-3493

ATTORNEY DOCKET NUMBER:	AUS920060440US1
NAME OF SUBMITTER:	D'Ann N. Rifai

Total Attachments: 4

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PATENT REEL: 020038 FRAME: 0713 CH \$40.00

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PATENT REEL: 020038 FRAME: 0714

ASSIGNMENT

WHEREAS, I, as a below named inventor, residing at the address stated next to my name, am a sole inventor (if only one name is listed below) or a joint inventor (if plural names are listed below) of certain new and useful improvements in: SYSTEM AND METHOD FOR GENERATING A WORST CASE CURRENT WAVEFORM FOR TESTING OF INTEGRATED CIRCUIT DEVICES

for which application for Letters Patent of the United States of America was executed by me on the date indicated next to my name and address;

AND WHEREAS, Sony Computer Entertainment Inc., a Japanese corporation with offices at 2-6-21, Minami-Aoyama, Minato-ku, Tokyo 107-0062, Japan, (hereinafter referenced as ASSIGNEE) is desirous of acquiring all interest in, to and under said invention, said application disclosing the invention and in, to and under any Letters Patent or similar legal protection which may be granted therefor in the United States and in any and all foreign countries;

NOW THEREFORE, in consideration of the sum of One Dollar (\$1.00), and other good and valuable consideration the receipt and sufficiency of which are hereby acknowledged. It as a solo or joint inventor as indicated below, by these presents do hereby assign, sell and transfer unto the said ASSIGNEE, its successors, assigns, and legal representatives, the entire right, title and interest in the said invention, said applications, including any divisions and continuations thereof, and in and to any and all Letters Patent of the United States, and countries foreign thereto, which may be granted for said invention, and in and to any and all priority rights and/or convention rights under the International Convention for the Protection of Industrial Property, Inter-American Convention Relating to Patent, Designs and Industrial Models, and any other international agreements to which the United States of America adheres, and to any other benefits accruing or to accrue to me with respect to the filing of applications for patents or securing of patents in the United States and countries foreign thereto, and I hereby authorize and request the Commissioner of Patents to issue the said United States Letters Patent to said ASSIGNEE, as the assignee of the whole right, title and interest thereto:

And I further agree to execute all necessary or desirable and lawful future documents, including assignments in favor of ASSIGNEE or its designee, as ASSIGNEE or its successors, assigns and legal representatives may from time-to-time present to me and without further remuneration, in order to perfect title in said invention, modifications, and improvements in said invention, applications and Letters Patent of the United States and countries foreign thereto;

And I further agree to properly execute and deliver and without further remuneration, such necessary or desirable and lawful papers for application for foreign patents, for filing subdivisions of said applications for patent, and/or, for obtaining any reissue or reissues of any Letters Patent which may be granted for my aforesaid invention, as the ASSIGNEE thereof shall hereafter require and prepare at its own expense;

And I further agree that ASSIGNEE will, upon its request, be provided promptly with all pertinent facts and documents relating to said application, said invention and said Letters Patent and legal equivalents in foreign countries as may be known and accessible to me and will testify as to the same in any interference or litigation related thereto;

And I hereby covenant that no assignment, sale, agreement or encumbrance has been or will be made or entered into which would conflict with this assignment and sale.

This assignment executed on the dates indicated below.

Makoto Aikawa	
Name of First or Sole Inventor	
c/o Sony Computer Entertainment Inc., 2-6-21 Min Residence of First or Sole Inventor	ami-Aoyama, Minato-ku, Tokyo 107-0062, Japan
Residence of Phst of Sole Inventor	
Makts alkana	Sept. 27, 2007
Maket Cikawa Signature of First or Sole Inventor	Date of this Assignment

Iwao Takiguchi Name of Second Inventor
c/o Sony Computer Entertainment Inc., 2-6-21 Minami-Aoyama, Minato-ku, Tokyo 107-0062, Japan Residence of Second Inventor
Signature of Second Inventor Date of this Assignment
Tetsuji Tamura Name of Third Inventor
c/o Sony Computer Entertainment Inc., 2-6-21 Minami-Aoyama, Minato-ku, Tokyo 107-0062, Japan Residence of Third Inventor
Signature of Third Inventor Date of this Assignment

PATENT REEL: 020038 FRAME: 0716

ASSIGNMENT

WHEREAS, I, as a below named inventor, residing at the address stated next to my name, am a sole inventor (if only one name is listed below) or a joint inventor (if plural names are listed below) of certain new and useful improvements in: SYSTEM AND METHOD FOR GENERATING A WORST CASE CURRENT WAVEFORM FOR TESTING OF INTEGRATED CIRCUIT DEVICES

for which application for Letters Patent of the United States of America was executed by me on the date indicated next to my name and address;

AND WHEREAS, Sony Computer Entertainment Inc., a Japanese corporation with offices at 2-6-21, Minami-Aoyama, Minato-ku, Tokyo 107-0062, Japan, (hereinafter referenced as ASSIGNEE) is desirous of acquiring all interest in, to and under said invention, said application disclosing the invention and in, to and under any Letters Patent or similar legal protection which may be granted therefor in the United States and in any and all foreign countries;

NOW THEREFORE, in consideration of the sum of One Dollar (\$1.00), and other good and valuable consideration the receipt and sufficiency of which are hereby acknowledged, I, as a solo or joint inventor as indicated below, by these presents do hereby assign, sell and transfer unto the said ASSIGNEE, its successors, assigns, and legal representatives, the entire right, title and interest in the said invention, said applications, including any divisions and continuations thereof, and in and to any and all Letters Patent of the United States, and countries foreign thereto, which may be granted for said invention, and in and to any and all priority rights and/or convention rights under the International Convention for the Protection of Industrial Property, Inter-American Convention Relating to Patent, Designs and Industrial Models, and any other international agreements to which the United States of America adheres, and to any other benefits accruing or to accrue to me with respect to the filing of applications for patents or securing of patents in the United States and countries foreign thereto, and I hereby authorize and request the Commissioner of Patents to issue the said United States Letters Patent to said ASSIGNEE, as the assignee of the whole right, title and interest thereto;

And I further agree to execute all necessary or desirable and lawful future documents, including assignments in favor of ASSIGNEE or its designee, as ASSIGNEE or its successors, assigns and legal representatives may from time-to-time present to me and without further remuneration, in order to perfect title in said invention, modifications, and improvements in said invention, applications and Letters Patent of the United States and countries foreign thereto;

And I further agree to properly execute and deliver and without further remuneration, such necessary or desirable and lawful papers for application for foreign patents, for filing subdivisions of said applications for patent, and/or, for obtaining any reissue or reissues of any Letters Patent which may be granted for my aforesaid invention, as the ASSIGNEE thereof shall hereafter require and prepare at its own expense;

And I further agree that ASSIGNEE will, upon its request, be provided promptly with all pertinent facts and documents relating to said application, said invention and said Letters Patent and legal equivalents in foreign countries as may be known and accessible to me and will testify as to the same in any interference or litigation related thereto:

And I hereby covenant that no assignment, sale, agreement or encumbrance has been or will be made or entered into which would conflict with this assignment and sale.

This assignment executed on the dates indicated below.

Makoto Aikawa Name of First or Sole Inventor	
c/o Sony Computer Entertainment Inc., 2-6-21 Mi Residence of First or Sole Inventor	inami-Aoyama, Minato-ku, Tokyo 107-0062, Japan
Signature of First or Sole Inventor	Date of this Assignment

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\$11 # 1854 IBM Docket No. AUS920060440US1

Iwao Takiguchi	
Name of Second Inventor	
c/o Sony Computer Entertainment Inc., 2-6-21 Minami-Aoyama, Minato-ku, Tokyo 107-0062, Residence of Second Inventor	Japan
Residence of Second Inventor	•
A 1 P A X c1/10/20-7 Signature of Second Inventor Date of this Assignment	
Signature of Second Inventor Date of this Assignment	
Tetsuji Tamura	
Name of Third Inventor	
c/o Sony Computer Entertainment Inc., 2-6-21 Minami-Aoyama, Minato-ku, Tokyo 107-0062, Residence of Third Inventor	Japan
Residence of Third Inventor	•
× 周村哲司 × 27/09/2007	
Signature of Third Inventor Date of this Assignment	

PATENT REEL: 020038 FRAME: 0718

RECORDED: 10/30/2007